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(54) Title: WAFER POLISHING SYSTEM

(54) 发明名称: 一种晶圆抛光系统

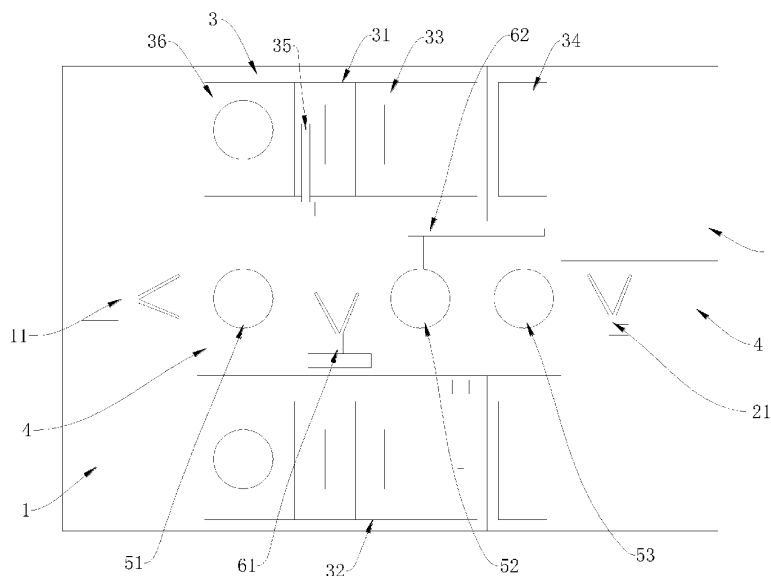


图 1

(57) Abstract: A wafer polishing system, comprising: a front-end module (1); a wafer polishing unit (2), comprising a polishing transmission mechanism (21); a wafer cleaning unit (3); and a wafer transmission channel (4) extending at least on the wafer cleaning unit (3). The front-end module (1), the wafer cleaning unit (3), and the wafer polishing unit (2) are sequentially arranged adjacent to each other; a first transfer station (51), a second transfer station (52), a third transfer station (53), a first transmission device (61), and a second transmission device (62) are provided in the wafer transmission channel (4); the first transmission device (61) is used for

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implementing wafer transmission between the first transfer station (51) and the second transfer station (52); the second transmission device (62) is used for implementing wafer transmission between the second transfer station (52) and the third transfer station (53); and the third transfer station (53) is further used for wafer transmission and transferring between the wafer cleaning unit (3) and the wafer polishing unit (2). The wafer transmission stroke in the wafer transmission channel (4) is divided into two sections which are respectively completed by the first transmission device (61) and the second transmission device (62), such that the volume is reduced, complex actions can be carried out in a narrow space, and the transmission speed is higher; and more process possibilities can be achieved by setting different transmission forms.

(57) 摘要: 一种晶圆抛光系统, 包括: 前端模块(1); 晶圆抛光单元(2), 包括有抛光传输机构(21); 晶圆清洗单元(3); 晶圆传输通道(4), 至少在晶圆清洗单元(3)延伸; 前端模块(1)、晶圆清洗单元(2)和晶圆抛光单元(3)依次相邻布设; 晶圆传输通道(4)内设有第一中转工位(51)、第二中转工位(52)、第三中转工位(53), 传输装置一(61)及传输装置二(62); 传输装置一(61)用于实现第一中转工位(51)、第二中转工位(52)之间的晶圆传输; 传输装置二(62)用于实现第二中转工位(52)、第三中转工位(53)之间的晶圆传输; 第三中转工位(53)还用于所述晶圆清洗单元(3)和晶圆抛光单元(2)之间的晶圆传输中转。将晶圆传输通道(4)内的晶圆传输行程分为两段, 分别由传输装置一(61)、传输装置二(62)完成, 体积减小, 其可以在狭小空间内进行复杂动作, 传输速度更快; 通过设置不同传输的形式可以实现更多工艺可能性。